# N-Channel SUPERFET<sup>®</sup> III Easy-Drive MOSFET

## 650 V, 24 A, 125 mΩ

#### Description

SuperFET III MOSFET is ON Semiconductor's brand-new high voltage super-junction (SJ) MOSFET family that is utilizing charge balance technology for outstanding low on-resistance and lower gate charge performance. This advanced technology is tailored to minimize conduction loss, provide superior switching performance, and withstand extreme dv/dt rate.

Consequently, SuperFET III MOSFET Easy-drive series helps manage EMI issues and allows for easier design implementation.

#### Features

- 700 V @  $T_J = 150^{\circ}C$
- Typ.  $R_{DS(on)} = 105 \text{ m}\Omega$
- Ultra Low Gate Charge (Typ.  $Q_g = 46 \text{ nC}$ )
- Low Effective Output Capacitance (Typ.  $C_{oss(eff.)} = 439 \text{ pF}$ )
- 100% Avalanche Tested
- These Devices are Pb-Free and are RoHS Compliant

### Applications

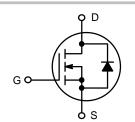
- Telecom/Sever Power Supplies
- Industrial Power Supply
- UPS/Solar



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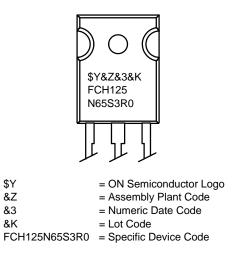
V <sub>DSS</sub>	R <sub>DS(ON)</sub> MAX	I <sub>D</sub> MAX
650 V	125 mΩ @ 10 V	24 A



N-Channel MOSFET



### MARKING DIAGRAM



### ORDERING INFORMATION

See detailed ordering and shipping information on page 2 of this data sheet.

Symbol	Parameter		Value	Unit
V <sub>DSS</sub>	Drain to Source Voltage	650	V	
V <sub>GSS</sub>	Gate to Source Voltage	DC	±30	V
		AC (f > 1 Hz)	±30	V
۱ <sub>D</sub>	Drain Current	Continuous ( $T_C = 25^{\circ}C$ )	24	A
		Continuous (T <sub>C</sub> = 100°C)	15	
I <sub>DM</sub>	Drain Current	Pulsed (Note 1)	60	А
E <sub>AS</sub>	Single Pulsed Avalanche Energy (Note 2)		115	mJ
I <sub>AS</sub>	Avalanche Current (Note 2)		3.7	А
E <sub>AR</sub>	Repetitive Avalanche Energy (Note 1)		1.81	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)		20	
PD	Power Dissipation	(T <sub>C</sub> = 25°C)	181	W
		Derate Above 25°C	1.45	W/°C
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Temperature Range		-55 to +150	°C
ΤL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 s		300	°C

#### ABSOLUTE MAXIMUM RATINGS (T<sub>C</sub> = 25°C, Unless otherwise specified)

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

1. Repetitive rating: pulse-width limited by maximum junction temperature. 2.  $I_{AS} = 3.7 \text{ A}, R_G = 25 \Omega$ , starting  $T_J = 25^{\circ}\text{C}$ . 3.  $I_{SD} \le 12 \text{ A}, \text{ di/dt} \le 200 \text{ A/}\mu\text{s}, \text{ V}_{DD} \le 400 \text{ V}, \text{ starting } T_J = 25^{\circ}\text{C}$ .

#### THERMAL CHARACTERISTICS

Symbol	Parameter	Value	Unit
$R_{ extsf{ heta}JC}$	Thermal Resistance, Junction to Case, Max.	0.69	°C/W
R <sub>θJA</sub>	Thermal Resistance, Junction to Ambient, Max.	40	0/11

#### PACKAGE MARKING AND ORDERING INFORMATION

Part Number	Top Marking	Package	Quantity
FCH125N65S3R0-F155	FCH125N65S3R0	TO-247-3LD (Pb-Free)	30 Units / Tube

### **ELECTRICAL CHARACTERISTICS** ( $T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHARACT	ERISTICS	•		•		
BV <sub>DSS</sub> Drain to Source Breakdown	Drain to Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 1 \text{ mA}, \text{ T}_{J} = 25^{\circ}\text{C}$	650	-	-	V
		$V_{GS} = 0 \text{ V}, \text{ I}_{D} = 1 \text{ mA}, \text{ T}_{J} = 150^{\circ}\text{C}$	700	-	-	V
$\Delta \text{BV}_{\text{DSS}}\!/\!\Delta\text{T}_{\text{J}}$	Breakdown Voltage Temperature Coefficient	$I_D$ = 1 mA, Referenced to 25°C	-	0.68	-	V/°C
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	$V_{DS} = 650 \text{ V}, V_{GS} = 0 \text{ V}$	-	-	1	μΑ
		$V_{DS} = 520 \text{ V}, \text{ T}_{C} = 125^{\circ}\text{C}$	-	1.35	-	
I <sub>GSS</sub>	Gate to Body Leakage Current	$V_{GS} = \pm 30$ V, $V_{DS} = 0$ V	-	-	±100	nA
N CHARACTE	ERISTICS	•	•			
V <sub>GS(th)</sub>	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 2.4 \text{ mA}$	2.5	-	4.5	V
R <sub>DS(on)</sub>	Static Drain to Source On Resistance	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12 A	-	105	125	mΩ
<b>9</b> FS	Forward Transconductance	V <sub>DS</sub> = 20 V, I <sub>D</sub> = 12 A	-	16	-	S
YNAMIC CHA	RACTERISTICS	•	•			
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 400 \text{ V}, V_{GS} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$	-	1940	-	pF
C <sub>oss</sub>	Output Capacitance	1	-	40	-	pF
Coss(eff.)	Effective Output Capacitance	$V_{DS} = 0 V$ to 400 V, $V_{GS} = 0 V$	-	439	-	pF
C <sub>oss(er.)</sub>	Energy Related Output Capacitance	$V_{DS} = 0 V$ to 400 V, $V_{GS} = 0 V$	-	62	-	pF
Q <sub>g(tot)</sub>	Total Gate Charge at 10V	$V_{DS} = 400 \text{ V}, \text{ I}_{D} = 12 \text{ A}, \text{ V}_{GS} = 10 \text{ V}$	-	46	-	nC
Q <sub>gs</sub>	Gate to Source Gate Charge	(Note 4)	-	12	-	nC
Q <sub>gd</sub>	Gate to Drain "Miller" Charge		-	19	-	nC
ESR	Equivalent Series Resistance	f = 1 MHz	-	0.5	-	Ω
WITCHING CH	IARACTERISTICS	•	•			
t <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD} = 400 \text{ V}, I_D = 12 \text{ A},$	-	21	-	ns
tr	Turn-On Rise Time	$V_{GS} = 10 \text{ V}, \text{ R}_{g} = 4.7 \Omega$ (Note 4)	-	19	-	ns
t <sub>d(off)</sub>	Turn-Off Delay Time		-	48	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	4.6	-	ns
OURCE-DRAI	N DIODE CHARACTERISTICS	•	•			
I <sub>S</sub>	Maximum Continuous Source to Drain Diode Forward Current		-	-	24	Α
I <sub>SM</sub>	Maximum Pulsed Source to Drain Diode Forward Current		-	-	60	Α
V <sub>SD</sub>	Source to Drain Diode Forward Voltage	$V_{GS} = 0 \text{ V}, \text{ I}_{SD} = 12 \text{ A}$	-	-	1.2	V
t <sub>rr</sub>	Reverse Recovery Time	$V_{GS} = 0 V$ , $I_{SD} = 12 A$ , $dI_F/dt = 100 A/\mu s$	-	339	-	ns
Q <sub>rr</sub>	Reverse Recovery Charge		-	5.7	-	μC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Essentially independent of operating temperature typical characteristics.

### **TYPICAL PERFORMANCE CHARACTERISTICS**

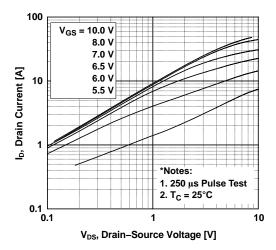


Figure 1. On-Region Characteristics

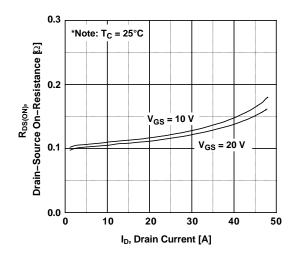


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

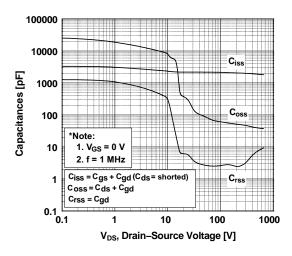
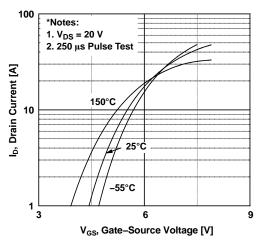


Figure 5. Capacitance Characteristics



**Figure 2. Transfer Characteristics** 

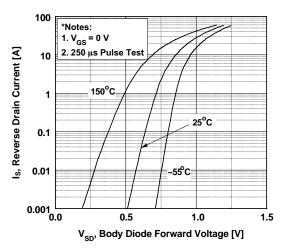


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

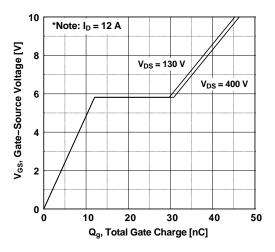


Figure 6. Gate Charge Characteristics

### TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

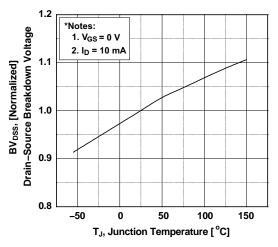


Figure 7. Breakdown Voltage Variation vs. Temperature

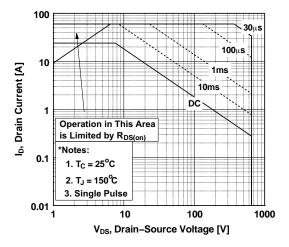


Figure 9. Maximum Safe Operation Area

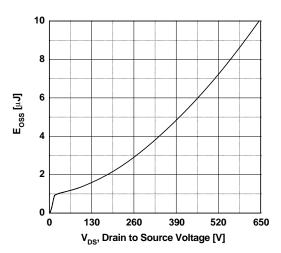


Figure 11. E<sub>OSS</sub> vs. Drain to Source Voltage

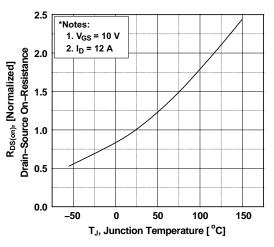


Figure 8. On-Resistance Variant vs. Temperature

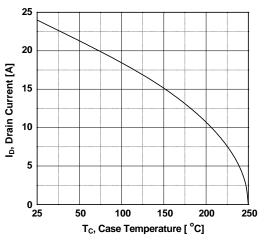


Figure 10. Maximum Drain Current vs. Case Temperature

### TYPICAL PERFORMANCE CHARACTERISTICS (Continued)

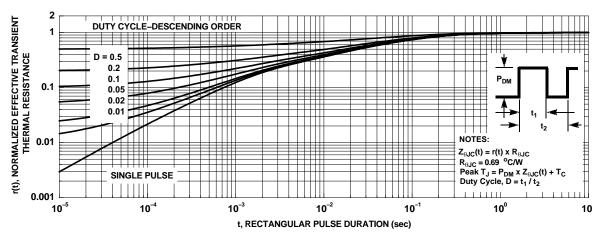
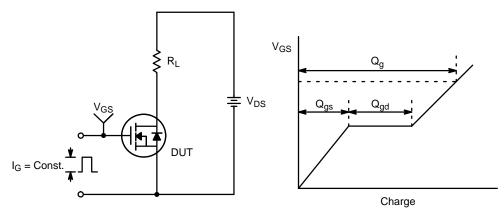


Figure 12. Transient Thermal Response Curve





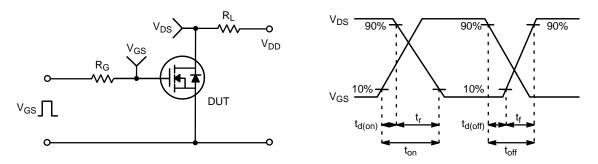


Figure 14. Resistive Switching Test Circuit & Waveforms

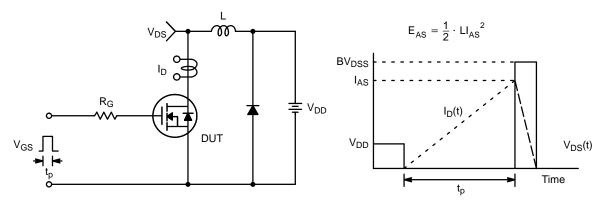


Figure 15. Unclamped Inductive Switching Test Circuit & Waveforms

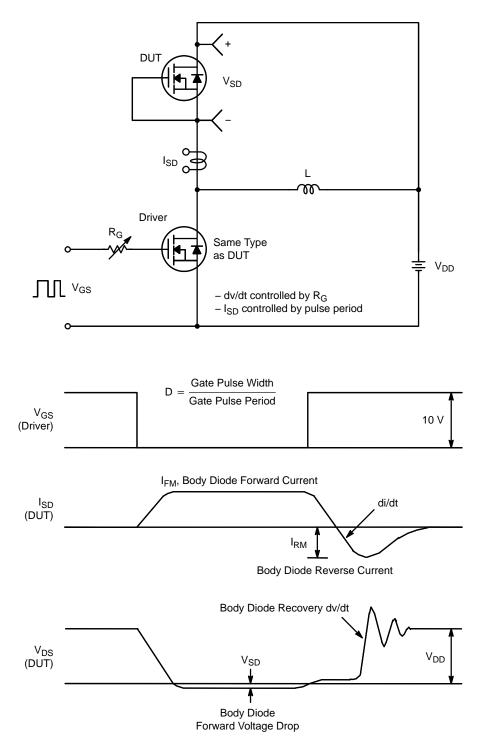
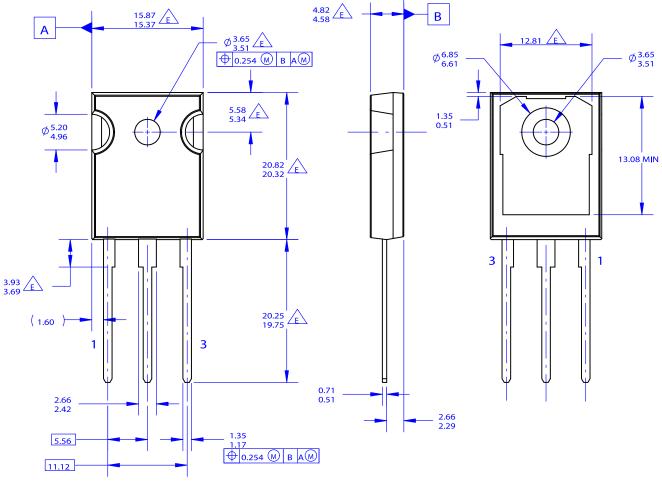


Figure 16. Peak Diode Recovery dt/dt Test Circuit & Waveforms

### PACKAGE DIMENSIONS

TO-247-3LD CASE 340CH ISSUE O



NOTES: UNLESS OTHERWISE SPECIFIED.

A. PACKAGE REFERENCE: JEDEC TO-247,

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FLASH, AND TIE BAR EXTRUSIONS.

C. ALL DIMENSIONS ARE IN MILLIMETERS.

D. DRAWING CONFORMS TO ASME Y14.5 - 1994

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